

TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

ETAS ID: TM422463

SUBMISSION TYPE:	NEW ASSIGNMENT		
NATURE OF CONVEYANCE:	RELEASE OF SECURITY INTEREST		
CONVEYING PARTY DATA			
Name	Formerly	Execution Date	Entity Type
Silicon Valley Bank		04/04/2017	Corporation: CALIFORNIA
RECEIVING PARTY DATA			
Name:	Endwave Corporation		
Street Address:	130 Baytech Drive		
City:	San Jose		
State/Country:	CALIFORNIA		
Postal Code:	95134		
Entity Type:	Corporation: DELAWARE		
PROPERTY NUMBERS Total: 1			
Property Type	Number	Word Mark	
Registration Number:	2496013	ENDWAVE	
CORRESPONDENCE DATA			
Fax Number:	80091442		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>			
Phone:	614-280-3568		
Email:	John.Salvage@wolterskluwer.com		
Correspondent Name:	CT Corporation System		
Address Line 1:	4400 Easton Commons Way		
Address Line 2:	Suite 125		
Address Line 4:	Columbus, OHIO 43219		
NAME OF SUBMITTER:	Elaine Carrera		
SIGNATURE:	/Elaine Carrera/		
DATE SIGNED:	04/04/2017		
Total Attachments: 5			
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**RELEASE OF SECURITY INTEREST IN
INTELLECTUAL PROPERTY**

This RELEASE, dated as of April 4, 2017, is made by Silicon Valley Bank (the "Secured Party"), pursuant to that certain Amended and Restated Security Agreement dated as of April 5, 2016 (the "Security Agreement") and that certain Third Amended and Restated Loan and Security Agreement dated as of April 5, 2016 (the "Amended Security Agreement").

WITNESSETH

WHEREAS, Endwave Corporation, a Delaware corporation (the "Grantor") is party to the Security Agreement;

WHEREAS, pursuant to the Security Agreement, the Grantor executed that certain Intellectual Property Security Agreement dated as of December 9, 2011 and recorded with the U.S. Patent and Trademark Office on December 12, 2011 at Reel/Frame No. 4676/0654, and that certain Amended and Restated Intellectual Property Security Agreement dated as of April 5, 2016 and recorded with the U.S. Patent and Trademark Office on April 6, 2016 at Reel/Frame No. 038372/0393 with respect to the patents and patent applications assigned, and at Reel/Frame No. 5766/0681 with respect to the trademarks and trademark applications assigned (collectively, the "Intellectual Property Security Agreements"), pursuant to which the Grantor granted to the Secured Party a security interest in all of its right, title and interest in and to, among other intellectual property, the intellectual property set forth in Schedule I attached hereto (the "Patent and Trademark Collateral");

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the Secured Party agrees as follows:

The Secured Party hereby TERMINATES, without recourse, representation or warranty the Intellectual Property Security Agreement and the Amended and Restated Intellectual Property Security Agreement, and RELEASES, without recourse, representation or warranty its security interest in the Patent and Trademark Collateral, including the patents, trademark and patent applications set forth in Schedule I.

[SIGNATURE PAGE FOLLOWS]

IN WITNESS WHEREOF, the Secured Party has caused this Release to be duly executed and delivered as of the date first written above.

Silicon Valley Bank, as Secured Party

By: 

Name: Janice Ahn

Title: Vice President

SCHEDULE I
to
RELEASE OF SECURITY INTEREST IN PATENT AND TRADEMARK COLLATERAL

Endwave Corp. - U.S. Patents

PATENT NO.	ISSUE DATE	TITLE
6,194,981	2001-02-27	Slot line band reject filter
6,600,384	2003-07-29	Impedance-compensating circuit
6,640,423	2003-11-04	Apparatus and method for the placement and bonding of a die on a substrate
7,006,794	2006-02-28	Wireless point to multi-point communication apparatus and method
7,109,583	2006-09-19	Mounting with auxiliary bumps
7,119,633	2006-10-10	Compensated interdigitated coupler
7,145,414	2006-12-05	Transmission line orientation transition
7,276,988	2007-10-02	Multi-substrate microstrip to waveguide transition
7,348,666	2008-03-25	Chip-to-chip trench circuit structure
7,411,279	2008-08-12	Component interconnect with substrate shielding
7,588,966	2009-09-15	Chip mounting with flowable layer
7,710,219	2010-05-04	Merged-filter multiplexer
7,813,145	2010-10-12	Circuit structure with multifunction circuit cover
D453,152	2002-01-29	Shaped reflector surface of a microwave antenna
D453,925	2002-02-26	Shaped reflector surface of microwave antenna
D453,927	2002-02-26	Shaped reflector surface of a microwave antenna
4,965,539	1990-10-23	Microwave notch filter using pin diode shunted YIG resonators
4,965,967	1990-10-30	Apparatus for low stress polishing of spherical objects
5,491,449	1996-02-13	Dual-sided push-pull amplifier
5,698,469	1997-12-16	Method of making a hybrid circuit with a chip having active devices with extra-chip interconnections
5,528,203	1996-06-18	Coplanar waveguide-mounted flip chip
5,563,558	1996-10-08	Reentrant power coupler
5,771,449	1998-06-23	Sectorized multi-function communication system
5,623,231	1997-04-22	Push-pull power amplifier
5,610,563	1997-03-11	Slot line to CPW circuit structure
5,789,801	1998-08-04	Varactor with electrostatic barrier
5,668,512	1997-09-16	Coplanar waveguide-mounted flip chip having coupled ground conductors
6,023,209	200-02-08	Coplanar microwave circuit having suppression of undesired modes
5,832,376	1998-11-03	Coplanar mixer assembly
5,942,804	1999-08-24	Circuit structure having a matrix of active devices
5,770,987	1998-06-23	Coplanar waveguide strip band pass filter
5,821,815	1998-10-13	Miniature active conversion between slotline and coplanar waveguide
5,978,666	1999-11-02	Slotline-mounted flip chip structures
5,983,089	1999-11-09	Slotline-mounted flip chip
5,760,650	1998-06-02	Coplanar waveguide amplifier
RE35869	1998-08-11	Miniature active conversion between microstrip and coplanar wave guide
5,942,957	1998-08-24	Flip-mounted impedance

6,002,305	1999-12-14	Transition between circuit transmission line and microwave waveguide
6,023,206	2000-02-08	Slot line band pass filter
6,052,582	2000-04-18	Sectorized multi-function communication system
6,064,253	2000-05-16	Multiple stage self-biasing RF transistor circuit
6,094,114	2000-07-25	Slotline-to-slotline mounted flip chip
6,194,981	2001-02-27	Slot line band reject filter
6,034,580	2000-03-07	Coplanar waveguide filter
6,265,937	2001-07-24	Push-pull amplifier with dual coplanar transmission line
6,640,423	2003-11-04	Apparatus and method for the placement and bonding of a die on a substrate
7,006,794	2006-02-28	Wireless point to multi-point communication apparatus and method
5,821,827	1998-10-13	Coplanar oscillator circuit structures
6,600,384	2003-07-29	Impedance-compensating circuit
7,109,583	2006-19-19	Mounting with auxiliary bumps

Endwave Corp. - U.S. Patent Applications

APPLICATION NO.	FILING DATE	TITLE
09/911,183	2001-07-23	Tunable resonator and method of tuning the same
09/946,972	2001-09-04	Waveguide mixer/coupler
10/010,527	2000-03-07	Filter cartridge comprises ring-shaped filter member with base and outer support ring
10/613,882	2003-07-02	N-way signal divider
10/882,886	2004-06-30	Electromagnetic shield assembly
11/777,096	2007-07-12	Compensated attenuator
12/038,546	2008-02-27	Coaxial-to-microstrip transitions and manufacturing methods
12/391,144	2009-02-23	Distributed amplifier with negative feedback
12/042,144	2006-06-26	Compensated attenuator
11/692,129	2007-03-27	Electromagnetic shield assembly

Endwave Corp. - U.S. Trademarks

REGISTRATION NO.	REGISTRATION DATE	TRADEMARK
2496013	2001-10-09	ENDWAVE